

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("20030201520").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/22 09:45
S1	1	"10581263"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/18 19:28
S2	1	"10581263"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/15 17:27
S8	2	"5055892".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 20:04
S9	2	("20040084687").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 20:05
S10	0	"10462089"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 20:14
S13	2	"6803607".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 20:18
S14	3	"6,800,932".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 14:38

S15	0	"10601,121"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 14:43
S16	4	"10/601,121"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 14:43
S17	77840	(lead near frame) or lead-frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 14:50
S18	55568	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 14:51
S19	14155	(lateral near power near transistor) or (power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:37
S20	7535	S19 and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:38
S21	77840	(lead near frame) or lead-frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:42
S22	55568	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:42

S23	173	S21 and S22 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:42
S24	72	S23 and encapsulate\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:43
S25	36	S24 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/16 16:57
S26	14155	(lateral near power near transistor) or (power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S27	7535	S26 and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S28	77840	(lead near frame) or lead-frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S29	55568	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S30	173	S28 and S29 and S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24

S31	72	S30 and encapsulate\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S32	36	S31 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S33	0	S32 and ((lateral near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S34	0	S32 and ((lateral planar) near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S35	19	S32 and ((lateral planar) same MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:24
S36	302	(lateral near power near (transistor or MOSFET))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:29
S37	170	S36 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 10:30
S38	58	(lateral same MOSFET) and (solder near (ball bump)) and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:03
S39	3	("6683380" "6710441"). PN. OR ("6972464"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 12:14

S40	60	("20010035746" "20010038277" "20020104872" "4175240" "4256977" "4462041" "4710349" "4794441" "4955790" "5038194" "5143865" "5148064" "5298797" "5470795" "5479089" "5479117" "5493275" "5532179" "5548150" "5608616" "5652183" "5726872" "5728594" "5736766" "5744843" "5777383" "5859456" "5900764" "5910669" "5946202" "5969513" "5973367" "6020729" "6023155" "6031361" "6097064" "6100583" "6100676" "6114726" "6150150" "6150722" "6160441" "6198261" "6225795" "6268716" "6271651" "6278264" "6288919" "6329801" "6351108" "6404173" "6421262" "6462521" "6462522" "6476442" "6476443").PN. OR ("6710441").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 12:14
S41	14155	(lateral near power near transistor) or (power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S42	7535	S41 and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S43	77840	(lead near frame) or lead- frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S44	55568	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22

S45	173	S43 and S44 and S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S46	72	S45 and encapsulate\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S47	36	S46 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:22
S48	78	S45 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 12:32
S49	5	("20010045635").PN. OR ("6649961").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 12:41
S50	244	(lateral near power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 13:27
S51	137	S50 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 13:28
S52	123	S51 and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 13:29
S53	2	S43 and S44 and S52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 13:30

S54	2	"6,278,264".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 13:41
S55	22	("4074342" "5671121" "5777383" "5959442"). PN. OR ("6278264"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 13:43
S56	11	("4811075" "5382825" "5432370" "5475258" "6153916" "6262454"). PN. OR ("6525390"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 14:08
S57	0	(lateral near power near mosfet).ti. and (flip-chip or flipchip or (flip near chip))	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 14:18
S58	14	(lateral near power near mosfet).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/17 14:18
S59	22	("20020093062" "20040164350" "4199774" "4574209" "4656493" "5119159" "5192989" "5381025" "5539238" "5723891" "5910664").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/17 14:26
S60	12140	power near MOSFET	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/17 14:30
S61	14108	power near MOSFET	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 14:30
S62	172	S42 and S61 and S43 and S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 14:31
S63	78	S62 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 14:31

S64	1326	257/e23.039.ccls. and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 14:39
S65	65	257/e23.039.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead- frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 14:40
S66	0	257/e23.045.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:11
S67	18	257/e23.048.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:12
S68	0	257/177.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:17
S69	3	257/341.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:17
S70	0	257/342.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:18
S71	0	257/343.ccls. and @ad<"20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:18

S72	74	257/676.ccls. and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:18
S73	12	257/676.ccls. and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger) and source and drain and gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:28
S74	8	257/737.ccls. and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger) and source and drain and gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:31
S75	10	257/778.ccls. and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger) and source and drain and gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:33
S76	14108	(power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:35
S77	57964	MOSFET and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:37
S78	77840	(lead near frame) or lead- frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:38
S79	55568	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:38

S80	232	S77 and S78 and S79	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:38
S81	109	S80 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/17 16:38
S82	14175	(lateral near power near transistor) or (power near MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14
S83	7550	S82 and (gate and source and drain)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14
S84	77868	(lead near frame) or lead-frame	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14
S85	55629	(pillar near bump\$1) or (solder near (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14
S86	173	S84 and S85 and S83	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14
S87	78	S86 and @ad<"20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 12:14

S88	738	(power near MOSFET) same lateral	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 16:10
S89	1	"10581263"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 16:59
S90	20	((power near MOSFET) same lateral) and (source and drain and gate) and (bump\$1 or (solder near (ball\$1 or bump\$1))) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 17:01
S91	7	("5321303" "5723907" "5844304").PN. OR ("6075279").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/18 17:16
S92	9	("4970579" "5578841" "5578869" "5629835" "5729052" "5757081" "5990552" "6075279" "6215290").PN. OR ("6894397").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/18 17:25
S93	3	"6338504"	US-PGPUB; USPAT; USOCR	OR	ON	2008/09/18 17:29
S94	10	(power near MOSFET) and (source and drain and gate) and (leadframe lead- frame) and (encapsulate "mold compound" "mold- compound" "epoxy mold" "mold epoxy") and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 17:35
S95	17	10/271,654,	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 17:46
S96	18	("5319242" "5841197" "5841197" "6133634" "6143981" "6255722" "6469384" "6476481" "6489678" "6569764"). PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 17:52

S97	21	("20020066950" "20020066959" "20020100962" "20020125550" "20020192935" "20040063240" "5319242" "5841197" "6133634" "6143981" "6242800" "6255722" "6469384" "6476481" "6489678" "6569764" "6624522" "6777800" "6812516" "6943434" "7119424").PN. OR ("7332806").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/18 18:14
S98	455	257/676.ccls. and (bump or (solder near ball)) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 18:21
S99	27	257/676.ccls. and (bump or (solder near ball)) and @ad< "20031203" and (source and drain and gate) and MOSFET	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 18:21
S100	2	LDMOS and (bump or (solder near ball)) and @ad< "20031203" and (source and drain and gate) and (leadframe lead- frame) and ("mold compound" "mold- compound" "mold epoxy" "epoxy mold")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 18:30
S101	9	LDMOS and (bump or (solder near ball)) and @ad< "20031203" and (source and drain and gate) and (leadframe lead- frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 18:37
S102	6	(Lateral near DMOS) and (bump or (solder near ball)) and @ad< "20031203" and (source and drain and gate) and (leadframe lead- frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/18 18:42

S103	22	("20010033020" "6144100" "6187660" "6207553" "6232662" "6235620" "6245663" "6248655" "6248658" "6252301" "6300237"). PN. OR ("6683380"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/18 18:48
S104	31	("20010033020" "20020192939" "20040113244" "20040124535" "20040132279" "20040166661" "20050000821" "20060145359" "20060199383" "4569729" "5051317" "5106461" "5169680" "5487819" "5707893" "6144100" "6383352" "6426011" "6458223" "6620731" "6638847" "6683380" "6852625" "6872590" "6915566" "6924224" "6936536" "6964887" "7008867" "7022609" "7034401"). PN. OR ("7411303"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/09/18 18:50
S105	2	("20030075786").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/18 18:55
S106	75	(LDMOS or (lateral near MOSFET) or MOSFET) and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger) and source and drain and gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 10:13
S107	11	(LDMOS or (lateral near MOSFET)) and @ad< "20031203" and (solder near (ball bump)) and (leadframe lead-frame lead-finger lead adj finger) and source and drain and gate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 10:52

S108	289	(LDMOS or (lateral near MOSFET)) and Packag\$3 and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 10:53
S109	0	S108 and (plastic same "mold compound" same ("con-conductive" "non conductive")) and (solder same ((tin Sn) or epoxy))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:08
S110	0	S108 and (plastic same "mold compound" same ("con-conductive" "non conductive")) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:09
S111	0	S108 and ("mold compound" same ("con-conductive" "non conductive")) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:09
S112	0	(LDMOS or (lateral near MOSFET)) and @ad< "20031203" and ("mold compound" same ("con-conductive" "non conductive")) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:10
S113	0	MOSFET and (plastic same "mold compound" same ("con-conductive" "non conductive")) and (solder same ((tin Sn) or epoxy))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:11
S114	0	(LDMOS or (lateral near MOSFET)) and @ad< "20031203" and ("mold compound" same ("con-conductive" "non conductive") same plastic) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:14
S115	0	MOSFET and @ad< "20031203" and ("mold compound" same ("con-conductive" "non conductive") same plastic) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:14

S116	0	(LDMOS or (lateral near MOSFET)) and @ad< "20031203" and ("mold compound" same ("non-conductive" "non conductive") same plastic) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:15
S117	4	(LDMOS or (lateral near MOSFET)) and @ad< "20031203" and (("mold compound" or "mold epoxy") same plastic) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 13:15
S118	0	(LDMOS HVMOS MOS) and @ad< "20031203" and (("mold compound" or "mold epoxy") same plastic) and solder and ("non-conductive" or non-conductive or non adj conductive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:23
S119	40	@ad< "20031203" and (("mold compound" or "mold epoxy") same plastic) and solder and ("non-conductive" or non-conductive or non adj conductive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:23
S120	8	@ad< "20031203" and (("mold compound" or "mold epoxy") same plastic same ("non-conductive" or non-conductive or non adj conductive)) and solder	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:30
S121	170	package and MOSFET and (multiple near chips) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/21 16:22
S122	215	package and MOSFET and (multiple near (chips die)) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/21 16:24
S123	305	package and MOSFET and (multiple near2 (chips die)) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/21 16:25

S124	43	package and (MOSFET near (die chips)) and (multiple near2 (chips die)) and @ad< "20031203"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/21 16:26
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